

軟板感光型防焊阻劑(LM-600 TSG1) Liquid Photo-imaginable Solder Mask

LM-600 TSG1 為一種接觸曝光鹼液顯影型之軟板防焊阻劑，為一性能優異的網印印刷油墨，顯影後忠於底片具有高度之解像力。此二液型感光防焊阻劑經高溫後硬化之塗膜具高絕緣性及高耐焊性，產品性質優越，適用於 FPCB 軟板精密製造。

LM-600 TSG1 series are screen-printing contact exposure type photo-imaginable mask designed for flexible printed circuit fabrication. It has sharp pattern, high resolution, high color stability for long baking time at high temperature and excellent electric properties. Also has fast curing speed, excellent printing properties and forming a tough protective film with excellent solder resist properties after post-curing for the production of FPCB which require fine pattern with high density packaging.

技術資料 Technical Data

1. 特性 FEATURES	LM-600 TSG1
顏色 Color	綠色
揮發性 Volatility content	25± 2 %
不揮發性 Solid content	75 ± 2 %
黏度(25℃) Viscosity at 25 °C (VT-04, #2 針, #2 Spindle)	A 劑 LM600 TSY1 (Component A):240±30PS B 劑 LM600-B TSH10 (Component B): 500±50PS
硬化條件 Curing Condition	紫外線曝光加熱後硬化 UV Exposure and thermal curing
絕緣 Electric properties	(A)誘電率：0.04 (B)絕緣破壞值：2.7KV/cm
耐焊錫性 Resistance to molten solder	260±5 °C , 10 秒 seconds, ≥3 次
鉛筆硬化(JIS K5400) Film hardness by pencil lead	≥6H
密著性(JIS D0202) Adhesion	100/100
貯存安定性 Shelf life at 20-30 °C under dark packing	6 個月 month

2. 作業流程 Operation conditions	
電路基板前處理 Pretreatment for PCBs	清刷、酸處理、水洗 Buff, Acid Cleaning and Washing
主劑加硬化劑混合	85 wt % A + 15 wt % B
塗佈 Coating	網印 Screen Printing (100~300 目)
預熱乾燥 Preheat drying	75°C 約 30 ~ 60 分鐘 75 °C about 30~60 minutes
曝光條件 UV Exposure	約 400 ~ 550 mJ/cm ² (依 21 格黑白底片曝至 9~11 格滿)
顯影條件 Imaging conditions	60~90 秒在 30±2 °C 的 1~2%碳酸鈉水溶液，水壓 1.5~2.0 kg/cm ² 60-90seconds at 30±2°C for 1-2 % Na ₂ CO ₃ aqueous solution
洗淨 Cleaning	水洗壓力 Water pressure : 2.0 ~ 2.5 kg/cm ²
後硬化 Post curing	150°C x 60 分鐘 minutes

以上各項數據僅供參考

The above information is for reference only.